



Material Content Data Sheet



Sales Product Name		TLE9867QXA20		Issued		27. September 2017		
MA#		MA001363254						
Package		PG-VQFN-48-31		Weight*		129.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.821	3.71	3.71	37099	37099
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		551	
	non noble metal	iron	7439-89-6	1.433	1.10		11029	
wire	non noble metal	copper	7440-50-8	58.193	44.78	45.95	447834	459552
	non noble metal	copper	7440-50-8	0.594	0.46	0.46	4572	4572
	encapsulation	organic material	carbon black	1333-86-4	0.181	0.14		1394
encapsulation	plastics	epoxy resin	-	7.669	5.90		59018	
	inorganic material	silicondioxide	60676-86-0	52.536	40.43	46.47	404296	464708
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	19981	19981
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4724	4724
glue	plastics	epoxy resin	-	0.280	0.22		2154	
	noble metal	silver	7440-22-4	0.937	0.72	0.94	7210	9364
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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